acc. to DIN EN 29454.1, 1.1.2.B, or DIN EN 61190-1-3, ROM1

Standard solder wire for manual soldering in electrical engineering, standard flux content 2.5 %.

Article No. (Nos. 1- 4)	Alloy	DIN EN 29453	DIN EN 61190	Melting range	Melting range
1884	Sn95,5Ag3,8Cu0,7	-	Sn96Ag04Cu0,7	217 °C eutectic	**lead-free**
1895	Sn97Ag3	S-Sn97Ag3	-	221 - 224 °C	
1894	Sn99,3Cu0,7	S-Sn99Cu1	Sn99Cu.7	227 °C eutectic	
1897	Sn97Cu3	S-Sn97Cu3	-	230 - 250 °C	
551894	Sn100Ni+	Fuji Patent	-	227 °C eutectic	
1860	Sn60Pb40	S-Sn60Pb40	Sn60Pb40	183 - 190 °C	lead-containing
1864	Sn60Pb38Cu2	S-Sn60Pb38Cu2	Sn60Pb38Cu02	183 - 190 °C	
1853	Pb50Sn50	S-Pb50Sn50	Sn50Pb50	183 - 215 °C	
1840	Pb60Sn40	S-Pb60Sn40	Sn40Pb60	183 - 235 °C	
1832	Pb70Sn30	S-Pb70Sn30	Sn30Pb70	183 - 255 °C	

Diameters

Article No. (Nos 5+6)	Ø in mm
18 . . 05 . .	0,50
18 . . 07 . .	0,75
18 . . 10 . .	1,00
18 . . 15 . .	1,50
18 . . 20 . .	2,00
18 . . 30 . .	3,00
18 . . 40 . .	4,00

Spools

Article No. (Nos 7+8)	Size
18 10	0,10 kg
18 20	0,25 kg
18 30	0,50 kg
18 40	1,00 kg
18 50	5,00 kg

Example for the article number: "18601040"

Nos 1+2	Nos 3+4	Nos 5+6	Nos 7+8
18	60	10	40
ISO-Core® "RA"	Sn60Pb40	Ø = 1,00mm	1,00 kg

For fine soldering in electronics, electrical engineering, telecommunications and electric motor construction.

FELDER ISO-Core® solder wires are produced similar to FELDER ISO-Tin® electronic grade solder alloys using the same high-purity alloy components according to international standards. The fluxing agents are characterised by their high thermal stability and the fact that they do not spatter during reflow! The light, solid flux residue of these solder wires does not cause corrosion with nonferrous metals. As a result, this residue does not have to be removed at the soldered joint.

Other available, halide activated solder wires according to DIN EN 29454.1, 1.1.2.B:

ISO-Core® "RA-05"
Mildly halide activated, also suitable for electronics to a certain extent, halogen content < 0.5%.

ISO-Core® "RA-AT"
Specifically developed for mechanical soldering with short cycles and high soldering temperatures, halogen content < 1.5%.